

## SECTION II—CLAIMS

1.-27. (Canceled)

28. (New) A method comprising:

providing a housing having two or more solder pins projecting therefrom;

positioning a frame on the housing such that the solder pins are received in a corresponding number of holes in the frame;

aligning the frame by moving it parallel and perpendicular to the solder pins, wherein the holes are sized relative to the solder pins such that the frame can be moved a selected distance perpendicular to the solder pins without the solder pins contacting the holes; and

soldering the solder pins within the holes.

29 (New) The method of claim 28 wherein a lens plate is contained within said frame.

30. (New) The method of claim 28 wherein said housing is part of an optical connector.

31. (New) The method of claim 28 wherein the housing comprises a substantially cylindrical body having an end face.

32. (New) The method of claim 31 wherein the solder pins project out from the end face.

33. (New) The method of claim 31 wherein the end face has an opening therein.
34. (New) The method of claim 28 wherein soldering the solder pins within the holes comprises depositing solder in the portions of the holes not occupied by the solder pins.